



Product Specification

Product:	Dielectric Paste
Part Number:	09L-WE03

Application Scope :

This paste is suitable for outer-layer encapsulation, chip bonding, and adhesion applications.

Usage Conditions :

Substrate	Thick-film circuits, glass, ceramics, metals, etc.
Usage Method	Printing, 200-250 mesh
Leveling	Let it level at room temperature for 5-10 minutes (adjust time based on actual leveling conditions).
Solidify	Furnace drying at 150–200°C for 20–30 minutes (the curing temperature can be within the range of 150–200°C, and the curing time may be adjusted according to actual conditions)
Thinner	ST-1001

Characteristics :

1. Paste Characteristics :

Characteristic	Standard	Test Method And Conditions
1 Fineness	$\leq 8\mu\text{m}$	FOG test
2 Viscosity	80~150Pa.s	Brookfield HBT (Boli Fei) viscometer, rotor SC4-14/6R, 10 rpm, $25\pm 1^\circ\text{C}$
3 Appearance	Achromatic colour	

2. Characteristics After Curing :

Under the condition of 1 sintering, Check fired film produced under the conditions specified in 1)

Characteristics	Standard	Test Method And Conditions
4 Acid Resistance	Fine	5% Sulfuric acid, no change after 30 minutes



5	Insulation Resistance	$\geq 10^4 \text{M}\Omega$	RCJ-30
6	Breakdown Voltage	$\geq 300\text{V}$	CS262673A

Save Conditions And Validity Period :

The product shall be stored in a sealed container at an ambient temperature of 5-15°C, with a shelf life of 1 year from the date of shipment.

Packaging Method :

Standard packaging, 1000g/can; samples are available in 200g small can packaging.